

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20050161774"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 11:39
S3	5	("5656552" "6114753" "6551676"). PN. OR ("6730595").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/02/28 12:11
S5	52	S4 not S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 12:15
S2	48	SUS304 and (25mm or ("25" near mm)) and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 12:15
S4	63	(storage near3 modulus) and (25mm or ("25" near mm)) and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 12:43
S6	649	(storage near3 modulus) and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 12:46
S11	4	"10242086"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:22

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S10	3	"2002053819"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:22
S8	253	S7 and ((adhesion or adhesive) with both with (side or surface) with (core or base or sheet or tape))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:34
S14	195	S13 not S8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:36
S13	271	S7 and ((adhesion or adhesive) with double with (side or sided or surface) with (core or base or sheet or tape))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:36
S15	67	S7 and S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:49
S9	9	S8 and S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 13:49
S7	44300	semiconductor and ((wafer or substrate) with (grinding or ground or thinning or thinned))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 14:04

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S17	63	semiconductor and (((wafer or substrate) with (grinding or ground or thinning or thinned)) same (temperature with "150"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 14:09
S19	4945	257/642,668,783,713,643,635.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 14:16
S18	56	S17 not S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 14:16
S20	188	S19 and @Pd>"20060801"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 14:32
S22	6	("6114753" "6699774" "6777310").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 15:24
S21	2132	438/459,460.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 15:24
S25	5078	428/343,345,354.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 16:05

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S24	2399	428/354.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 16:05
S16	14	semiconductor and (((wafer or substrate) with (grinding or ground or thinning or thinned)) same (degree with "150"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 16:05
S26	51	S25 and semiconductor and (((wafer or substrate) with (grinding or ground or thinning or thinned)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/28 16:06